Agilent Technologies
Innovating the HP Way

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CHANGE NOTICE FOR AGILENT TECHNOLOGIES CUSTOMERS

CCN#: HOC210

Please be advised that Agilent Technologies will be making the following product change(s) on the effective date noted for the products listed.

AGILENT PART NUMBERS

All Commercial and Hi-Rel Hermetic Optocouplers

EXTENT OF CHANGE:

Agilent Technologies is converting from 4” diameter wafers to 6” diameter wafers. The key difference is in the Base process. The 4” process utilized diffusion whereas the 6” utilizes an Ion implant process. There is no change to the die size, die thickness, masking or active areas of the die. Full qualification testing has been completed on products built with this change.

REASON FOR CHANGE:

This change is a process enhancement designed to address increasing manufacturing costs and higher demands.

EFFECTIVE DATE OF CHANGE:

Manufacturing use of the 6” wafers will be implemented upon depletion of the 4” wafer stock.

Please call Ann Harding at (408) 435-6707 if there are any questions or concerns.

Shelley A. Sinclair
Product Line Manager

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